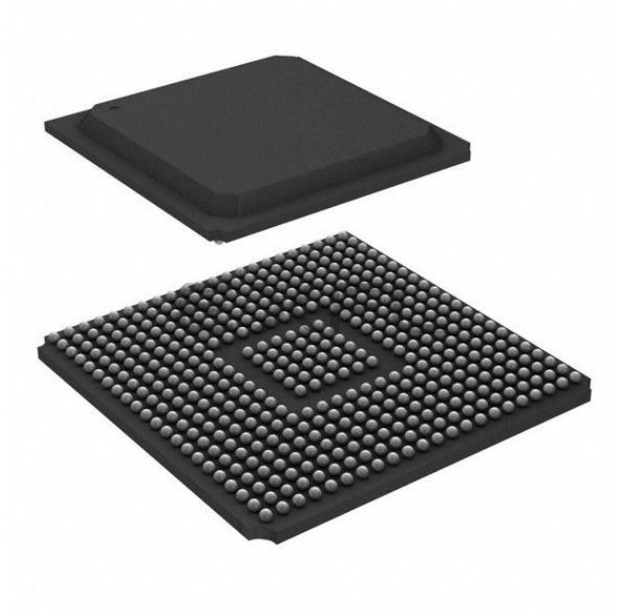

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	752
Number of Logic Elements/Cells	6768
Total RAM Bits	516096
Number of I/O	248
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	456-BBGA
Supplier Device Package	456-FBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp4-5fgg456i

CRC may adjust certain trailing bytes to generate the required running disparity at the end of the packet.

On the receiver side, the CRC logic verifies the received CRC value, supporting the same standards as above.

The CRC logic also supports a user mode, with a simple data packet stucture beginning and ending with user-defined SOP and EOP characters.

Loopback

In order to facilitate testing without having the need to either apply patterns or measure data at GHz rates, two programmable loop-back features are available.

One option, serial loopback, places the gigabit transceiver into a state where transmit data is directly fed back to the receiver. An important point to note is that the feedback path is at the output pads of the transmitter. This tests the entirety of the transmitter and receiver.

The second option, parallel loopback, checks the digital circuitry. When parallel loopback is enabled, the serial loopback path is disabled. However, the transmitter outputs remain active, and data can be transmitted. If TXINHIBIT is asserted, TXP is forced to 0 until TXINHIBIT is de-asserted.

Reset

The receiver and transmitter have their own synchronous reset inputs. The transmitter reset recenters the transmission FIFO, and resets all transmitter registers and the 8B/10B decoder. The receiver reset recenters the receiver elastic buffer, and resets all receiver registers and the 8B/10B encoder. Neither reset has any effect on the PLLs.

Power

All RocketIO transceivers in the FPGA, whether instantiated in the design or not, must be connected to power and ground. Unused transceivers can be powered by any 2.5V source, and passive filtering is not required.

Power Down

The Power Down module is controlled by the transceiver's POWERDOWN input pin. The Power Down pin on the FPGA package has no effect on the transceiver.

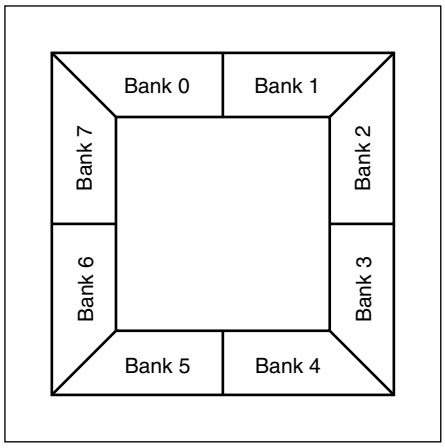


Figure 24: **I/O Banks: Wire-Bond Packages (FG) Top View**

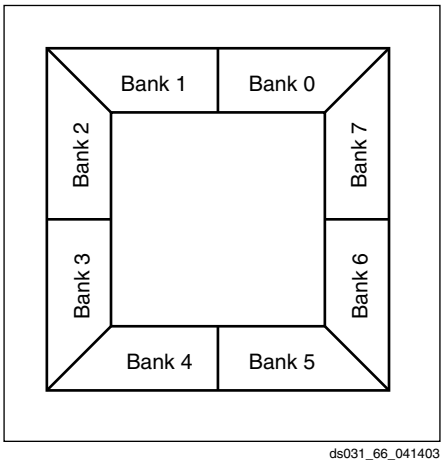


Figure 25: **I/O Banks: Flip-Chip Packages (FF) Top View**

Some input standards require a user-supplied threshold voltage (V_{REF}), and certain user-I/O pins are automatically configured as V_{REF} inputs. Approximately one in six of the I/O pins in the bank assume this role.

V_{REF} pins within a bank are interconnected internally, thus only one V_{REF} voltage can be used within each bank. However, for correct operation, all V_{REF} pins in the bank must be connected to the external reference voltage source.

The V_{CCO} and the V_{REF} pins for each bank appear in the device pinout tables. Within a given package, the number of V_{REF} and V_{CCO} pins can vary depending on the size of device. In larger devices, more I/O pins convert to V_{REF} pins. Since these are always a superset of the V_{REF} pins used for smaller devices, it is possible to design a PCB that permits migration to a larger device if necessary.

All V_{REF} pins for the largest device anticipated must be connected to the V_{REF} voltage and not used for I/O. In smaller devices, some V_{CCO} pins used in larger devices do not connect within the package. These unconnected pins can be left unconnected externally, or, if necessary, they can be connected to V_{CCO} to permit migration to a larger device.

Rules for Combining I/O Standards in the Same Bank

The following rules must be obeyed to combine different input, output, and bi-directional standards in the same bank:

1. **Combining output standards only.** Output standards with the same output V_{CCO} requirement can be combined in the same bank.
   Compatible example:
   SSTL2_I and LVDS_25 outputs
   Incompatible example:
   SSTL2_I (output V_{CCO} = 2.5V) and
   LVCMOS33 (output V_{CCO} = 3.3V) outputs
2. **Combining input standards only.** Input standards with the same input V_{CCO} and input V_{REF} requirements can be combined in the same bank.
   Compatible example:
   LVCMOS15 and HSTL_IV inputs
   Incompatible example:
   LVCMOS15 (input V_{CCO} = 1.5V) and
   LVCMOS18 (input V_{CCO} = 1.8V) inputs
   Incompatible example:
   HSTL_I_DCI_18 (V_{REF} = 0.9V) and
   HSTL_IV_DCI_18 (V_{REF} = 1.1V) inputs
3. **Combining input standards and output standards.** Input standards and output standards with the same input V_{CCO} and output V_{CCO} requirement can be combined in the same bank.
   Compatible example:
   LVDS_25 output and HSTL_I input
   Incompatible example:
   LVDS_25 output (output V_{CCO} = 2.5V) and
   HSTL_I_DCI_18 input (input V_{CCO} = 1.8V)
4. **Combining bi-directional standards with input or output standards.** When combining bi-directional I/O with other standards, make sure the bi-directional standard can meet rules 1 through 3 above.
5. **Additional rules for combining DCI I/O standards.**
   a. No more than one Single Termination type (input or output) is allowed in the same bank.
      Incompatible example:
      HSTL_IV_DCI input and HSTL_III_DCI input
   b. No more than one Split Termination type (input or output) is allowed in the same bank.
      Incompatible example:
      HSTL_I_DCI input and HSTL_II_DCI input

The implementation tools will enforce the above design rules.

Table 12, page 30, summarizes all standards and voltage supplies.

Table 15: **SelectIO-Ultra Differential Buffers With On-Chip Termination**

I/O Standard Description	IOSTANDARD Attribute	
	External Termination	On-Chip Termination
LVDS 2.5V	LVDS_25	LVDS_25_DCI
LVDS Extended 2.5V	LVDSEXT_25	LVDSEXT_25_DCI

Figure 28 provides examples illustrating the use of the HSTL_I_DCI, HSTL_II_DCI, HSTL_III_DCI, and HSTL_IV_DCI I/O standards. For a complete list, see the ***Virtex-II Pro Platform FPGA User Guide***.

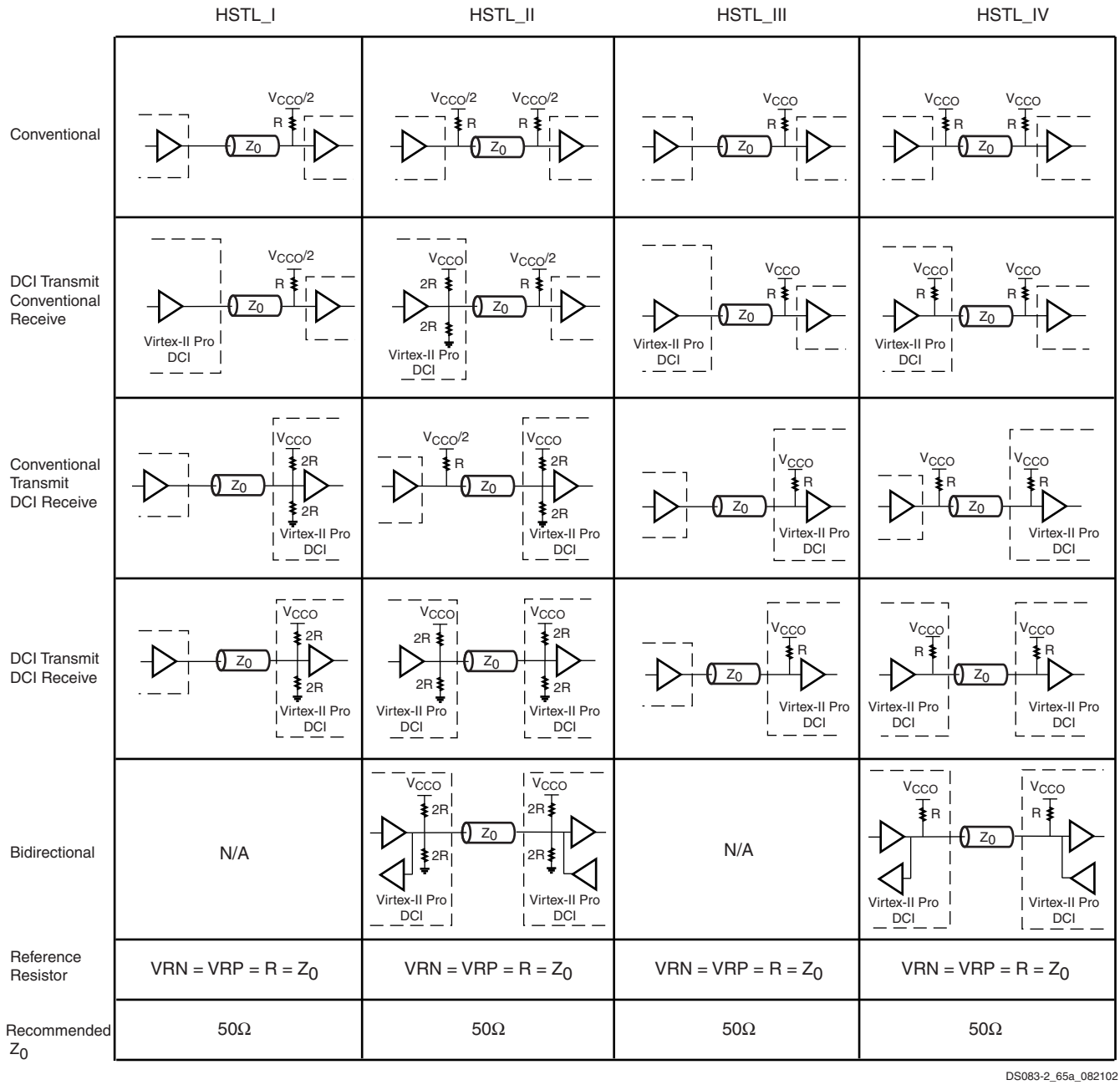


Figure 28: **HSTL DCI Usage Examples**

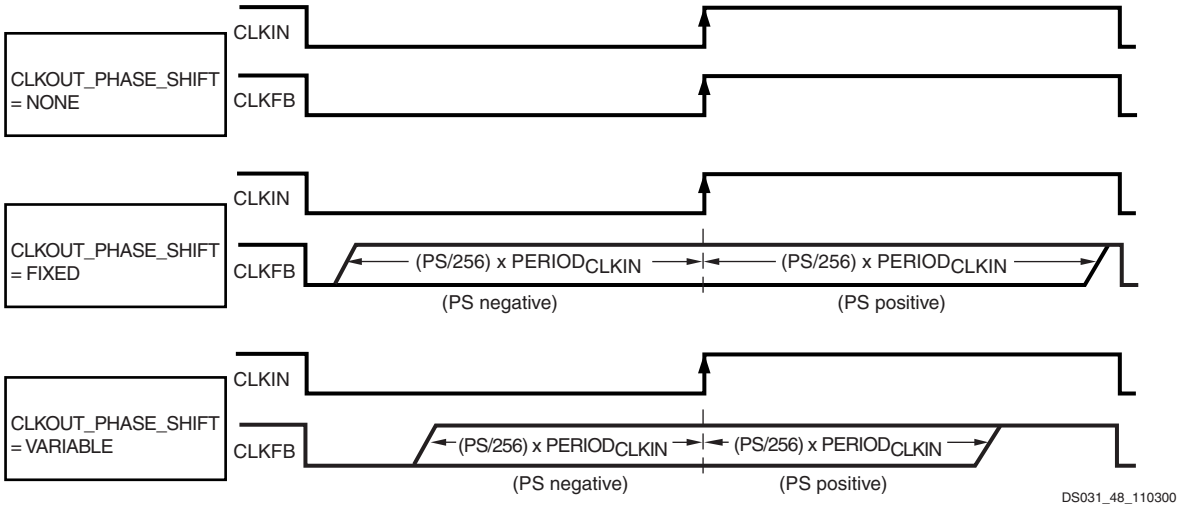


Figure 63: **Fine-Phase Shifting Effects**

Two separate components of the phase shift range must be understood:

- PHASE_SHIFT attribute range
- FINE_SHIFT_RANGE DCM timing parameter range

The PHASE_SHIFT attribute is the numerator in the following equation:

$$\text{Phase Shift (ns)} = (\text{PHASE\_SHIFT}/256) * \text{PERIOD}_{\text{CLKIN}}$$

The full range of this attribute is always -255 to +255, but its practical range varies with CLKIN frequency, as constrained by the FINE_SHIFT_RANGE component, which represents the total delay achievable by the phase shift delay line. Total delay is a function of the number of delay taps used in the circuit. Across process, voltage, and temperature, this absolute range is guaranteed to be as specified under **DCM Timing Parameters** in Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics.

Absolute range (fixed mode) = ± FINE_SHIFT_RANGE

Absolute range (variable mode) = ± FINE_SHIFT_RANGE/2

The reason for the difference between fixed and variable modes is as follows. For variable mode to allow symmetric, dynamic sweeps from -255/256 to +255/256, the DCM sets the "zero phase skew" point as the middle of the delay line, thus dividing the total delay line range in half. In fixed mode, since the PHASE_SHIFT value never changes after configuration, the entire delay line is available for insertion into either the CLKIN or CLKFB path (to create either positive or negative skew).

Taking both of these components into consideration, the following are some usage examples:

- If $\text{PERIOD}_{\text{CLKIN}} = 2 * \text{FINE\_SHIFT\_RANGE}$, then PHASE_SHIFT in fixed mode is limited to ± 128, and in variable mode it is limited to ± 64.
- If $\text{PERIOD}_{\text{CLKIN}} = \text{FINE\_SHIFT\_RANGE}$, then PHASE_SHIFT in fixed mode is limited to ± 255, and in variable mode it is limited to ± 128.
- If $\text{PERIOD}_{\text{CLKIN}} \leq 0.5 * \text{FINE\_SHIFT\_RANGE}$, then PHASE_SHIFT is limited to ± 255 in either mode.

Operating Modes

The frequency ranges of DCM input and output clocks depend on the operating mode specified, either low-frequency mode or high-frequency mode, according to Table 30. For actual values, see Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics. The CLK2X, CLK2X180, CLK90, and CLK270 outputs are not available in high-frequency mode.

High or low-frequency mode is selected by an attribute.

Table 30: **DCM Frequency Ranges**

Output Clock	Low-Frequency Mode		High-Frequency Mode	
	CLKIN Input	CLK Output	CLKIN Input	CLK Output
CLK0, CLK180	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_1X_LF	CLKIN_FREQ_DLL_HF	CLKOUT_FREQ_1X_HF
CLK90, CLK270	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_1X_LF	NA	NA
CLK2X, CLK2X180	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_2X_LF	NA	NA
CLKDV	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_DV_LF	CLKIN_FREQ_DLL_HF	CLKOUT_FREQ_DV_HF
CLKFX, CLKFX180	CLKIN_FREQ_FX_LF	CLKOUT_FREQ_FX_LF	CLKIN_FREQ_FX_HF	CLKOUT_FREQ_FX_HF

Table 27: **RocketIO Transmitter Switching Characteristics**

Description	Symbol	Conditions	Min	Typ	Max	Units
Serial data rate, full-speed clock	F_{GTX}	Flipchip packages	1.0		3.125(1)	Gb/s
		Wirebond packages	1.0		2.5(1)	Gb/s
Serial data rate, half-speed clock(3) (2X oversampling)		Flipchip packages	0.600		1.0	Gb/s
		Wirebond packages	0.600		1.0	Gb/s
Serial data output deterministic jitter	T_{DJ}	2.126 Gb/s – 3.125 Gb/s			0.17	UI(2)
		1.0626 Gb/s – 2.125 Gb/s			0.08	UI
		1.0 Gb/s – 1.0625 Gb/s			0.05	UI
		600 Mb/s – 999 Mb/s			0.08(4)	UI
Serial data output random jitter	T_{RJ}	2.126 Gb/s – 3.125 Gb/s			0.18	UI
		1.0626 Gb/s – 2.125 Gb/s			0.19	UI
		1.0 Gb/s – 1.0625 Gb/s			0.18	UI
		600 Mb/s – 999 Mb/s			0.18(4)	UI
TX rise time	T_{RTX}	20% – 80%		120		ps
TX fall time	T_{FTX}			120		ps
Transmit latency(5)	T_{TXLAT}	Including CRC		14	17	TXUSR CLK cycles
		Excluding CRC		8	11	
TXUSRCLK duty cycle	T_{TXDC}		45	50	55	%
TXUSRCLK2 duty cycle	T_{TX2DC}		45	50	55	%

Notes:
1. Serial data rate in the -5 speed grade is limited to 2.0 Gb/s in both wirebond and flipchip packages.
2. UI = Unit Interval
3. For serial rates under 1 Gb/s, the 3X (or greater) oversampling techniques described in **XAPP572** are required to meet the transmit jitter and receive jitter tolerance specifications defined in this data sheet.
4. The oversampling techniques described in **XAPP572** are required to meet these specifications for serial rates less than 1 Gb/s.
5. Transmit latency delay TXDATA to TXP/TXN. Refer to ***RocketIO Transceiver User Guide*** for more information on calculating latency.

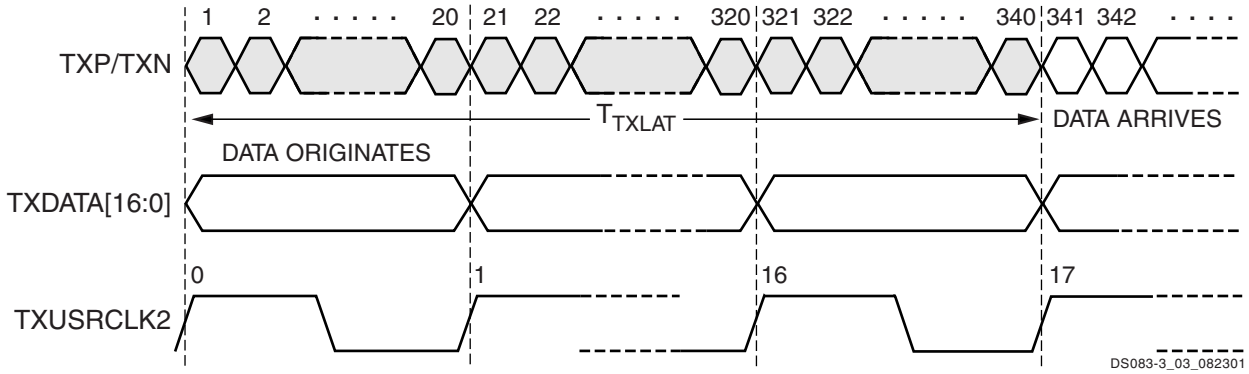


Figure 5: **RocketIO Transmit Latency (Maximum, Including CRC)**

Table 31: **RocketIO X RXUSRCLK2 Switching Characteristics *(Continued)***

		Speed Grade			
Description	**Symbol**	**-7**	**-6**	**-5**	**Units**
RXDEC64B66BUSE RXDEC8B10BUSE control input	$T_{GCCK\_}RDEC/T_{GCCK\_}RDEC$				ns, min
RXDESCRAM64B66BUSE control input	$T_{GCCK\_}RDES/T_{GCCK\_}RDES$				ns, min
RXINTDATAWIDTH control input	$T_{GCCK\_}RIDATW/T_{GCCK\_}RIDATW$				ns, min
RXSLIDE control input	$T_{GCCK\_}RXSLIDE/T_{GCCK\_}RXSLIDE$				ns, min
Clock to Out					
PMARXLOCK status output	$T_{GCKST\_}PLCK$				ns, max
RXNOTINTABLE status outputs	$T_{GCKST\_}RNIT$				ns, max
RXDISPERR status outputs	$T_{GCKST\_}RDERR$				ns, max
RXCHARISCOMMA status outputs	$T_{GCKST\_}RCMCH$				ns, max
RXREALIGN status output	$T_{GCKST\_}ALIGN$				ns, max
RXCOMMADET status output	$T_{GCKST\_}CMDT$				ns, max
RXLOSSOFSYNC status outputs	$T_{GCKST\_}RLOS$				ns, max
RXCLKCORCNT status outputs	$T_{GCKST\_}RCCCNT$				ns, max
RXBUFSTATUS status outputs	$T_{GCKST\_}RBSTA$				ns, max
CHBONDDONE status output	$T_{GCKST\_}CHBD$				ns, max
RXCHARISK status outputs	$T_{GCKST\_}RKCH$				ns, max
RXRUNDISP status outputs	$T_{GCKST\_}RRDIS$				ns, max
RXDATA data outputs	$T_{GCKDO\_}RDAT$				ns, max
Clock					
RXUSRCLK2 minimum pulse width, High	T_{RX2PWH}				ns, min
RXUSRCLK2 minimum pulse width, Low	T_{RX2PWL}				ns, min

Table 32: **RocketIO RXUSRCLK2 Switching Characteristics**

		Speed Grade			
Description	**Symbol**	**-7**	**-6**	**-5**	**Units**
Setup and Hold Relative to Clock (RXUSRCLK2)					
RXRESET control input	$T_{GCCK\_}RRST/T_{GCKC\_}RRST$	0.02/ 0.00	0.02/ 0.00	0.02/ 0.00	ns, min
RXPOLARITY control input	$T_{GCCK\_}RPOL/T_{GCKC\_}RPOL$	0.02/ 0.00	0.02/ 0.00	0.02/ 0.00	ns, min
ENCHANSYNC control input	$T_{GCCK\_}ECSY/T_{GCKC\_}ECSY$	0.02/ 0.00	0.02/ 0.00	0.02/ 0.00	ns, min
Clock to Out					
RXNOTINTABLE status outputs	$T_{GCKST\_}RNIT$	0.50	0.50	0.55	ns, max
RXDISPERR status outputs	$T_{GCKST\_}RDERR$	0.50	0.50	0.55	ns, max
RXCHARISCOMMA status outputs	$T_{GCKST\_}RCMCH$	0.50	0.50	0.55	ns, max
RXREALIGN status output	$T_{GCKST\_}ALIGN$	0.41	0.41	0.46	ns, max
RXCOMMADET status output	$T_{GCKST\_}CMDT$	0.41	0.41	0.46	ns, max
RXLOSSOFSYNC status outputs	$T_{GCKST\_}RLOS$	0.50	0.50	0.55	ns, max
RXCLKCORCNT status outputs	$T_{GCKST\_}RCCCNT$	0.41	0.41	0.46	ns, max

Virtex-II Pro Receiver Data-Valid Window (R_X)

R_X is the required minimum aggregate valid data period for a source-synchronous data bus at the pins of the device and is calculated as follows:

$$R_X = [TSAMP^{(1)} + TCKSKEW^{(2)} + TPKGSKEW^{(3)}]$$

Notes:

1. This parameter indicates the total sampling error of Virtex-II Pro DDR input registers across voltage, temperature, and process. The characterization methodology uses the DCM to capture the DDR input registers' edges of operation. These measurements include:
   - CLK0 and CLK180 DCM jitter in a quiet system
   - Worst-case duty-cycle distortion
   - DCM accuracy (phase offset)
   - DCM phase shift resolution.

   These measurements do not include package or clock tree skew.
2. This value represents the worst-case clock-tree skew observable between sequential I/O elements. Significantly less clock-tree skew exists for I/O registers that are close to each other and fed by the same or adjacent clock-tree branches. Use the Xilinx FPGA_Editor and Timing Analyzer tools to evaluate clock skew specific to your application.
3. These values represent the worst-case skew between any two balls of the package: shortest flight time to longest flight time from Pad to Ball.

Revision History

This section records the change history for this module of the data sheet.

Date	Version	Revision
01/31/02	1.0	Initial Xilinx release.
06/17/02	2.0	• Added new Virtex-II Pro family members. • Added timing parameters from speedsfile **v1.62**. • Added Table 46, Pipelined Multiplier Switching Characteristics. • Added 3.3V-vs-2.5V table entries for some parameters.
09/03/02	2.1	• Added Source-Synchronous Switching Characteristics section. • Added absolute max ratings for 3.3V-vs-2.5V parameters in Table 1. • Added recommended operating conditions for V_{IN} and RocketIO footnote to Table 2. • Updated SSTL2 values in Table 6. Added SSTL18 values: Table 6, Table 39, Table 32. [Table 32 removed in v2.8.] • Added Table 10, which contains LVPECL DC specifications.
09/27/02	2.2	Added section General Power Supply Requirements.
11/20/02	2.3	Updated parametric information in: • Table 1: Increase Absolute Max Rating for V_{CCO}, V_{REF}, V_{IN}, and V_{TS} from 3.6V to 3.75V. Delete cautionary footnotes related to voltage overshoot/undershoot. • Table 2: Delete V_{CCO} specifications for 2.5V and below operation. Delete footnote referencing special information for 3.3V operation. Add footnote for PCI/PCI-X. • Table 3: Add I_{BATT}. Delete I_L specifications for 2.5V and below operation. • Table 4: Add Typical Quiescent Supply Currents for XC2VP4 and XC2VP7 only • Table 6: Correct I_{OL} and I_{OH} for SSTL2 I. Add rows for LVTTL, LVCMOS33, and PCI-X. Correct max V_{IH} from V_{CCO} to 3.6V. • Table 7: Correct Min/Max V_{OD}, V_{OCM}, and V_{ICM} • Table 10: Reformat LVPECL DC Specifications to match Virtex-II data sheet format • Table 12: Correct parameter name from Differential Output Voltage to Single-Ended Output Voltage Swing. • Table 16: Add CPMC405CLOCK max frequencies • Table 27: Add footnote regarding serial data rate limitation in -5 part. • Table 39: Add rows for LVTTL, LVCMOS33, and PCI-X. • Table 32: Add LVTTL, LVCMOS33, and PCI-X. Correct all capacitive load values (except PCI/PCI-X) to 0 pF. [Table 32 removed in v2.8.] • Table 51: Correct CCLK max frequencies
11/25/02	2.4	Table 1: Correct lower limit of voltage range of V_{IN} and V_{TS} from –0.3V to –0.5V for 3.3V.

Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Pinout Information

DS083 (v5.0) June 21, 2011 **Product Specification**

This document provides Virtex™-II Pro Device/Package Combinations, Maximum I/Os, and Virtex-II Pro Pin Definitions, followed by pinout tables, for these packages:

- FG256/FGG256 Fine-Pitch BGA Package
- FG456/FGG456 Fine-Pitch BGA Package
- FG676/FGG676 Fine-Pitch BGA Package
- FF672 Flip-Chip Fine-Pitch BGA Package
- FF896 Flip-Chip Fine-Pitch BGA Package
- FF1152 Flip-Chip Fine-Pitch BGA Package
- FF1148 Flip-Chip Fine-Pitch BGA Package
- FF1517 Flip-Chip Fine-Pitch BGA Package
- FF1704 Flip-Chip Fine-Pitch BGA Package
- FF1696 Flip-Chip Fine-Pitch BGA Package

For device pinout diagrams and layout guidelines, refer to the **Virtex-II Pro Platform FPGA User Guide**. ASCII package pinout files are also available for download from the Xilinx website (**www.xilinx.com**).

Virtex-II Pro Device/Package Combinations and Maximum I/Os(1)

Wire-bond and flip-chip packages are available. Table 1 and Table 2 show the maximum number of user I/Os possible in wire-bond and flip-chip packages, respectively.

- FG denotes wire-bond fine-pitch BGA (1.00 mm pitch).
- FGG denotes Pb-free wire-bond fine-pitch BGA (1.00 mm pitch).
- FF denotes flip-chip fine-pitch BGA (1.00 mm pitch)

Table 1: **Wire-Bond Packages Information**

Package(1)	FG256/ FGG256	FG456/ FGG456	FG676/ FGG676
Pitch (mm)	1.00	1.00	1.00
Size (mm)	17 x 17	23 x 23	26 x 26
Maximum I/Os	140	248	412

Notes:
1. Wire-bond packages include FGG*nnn* Pb-free versions. See Virtex-II Pro Ordering Examples (Module 1).

Table 2: **Flip-Chip Packages Information**

Package	FF672	FF896	FF1152	FF1148	FF1517	FF1704	FF1696
Pitch (mm)	1.00	1.00	1.00	1.00	1.00	1.00	1.00
Size (mm)	27 x 27	31 x 31	35 x 35	35 x 35	40 x 40	42.5 x 42.5	42.5 x 42.5
Maximum I/Os	396	556	644	812	964	1040	1200

Table 3 shows the number of available I/Os, the number of RocketIO™ (or RocketIO X) multi-gigabit transceiver (MGT) pins, and the number of differential I/O pairs for each Virtex-II Pro device/package combination. The number of I/Os per package includes all user I/Os *except* the fifteen control pins (CCLK, DONE, M0, M1, M2, PROG_B, PWRDWN_B, TCK, TDI, TDO, TMS, HSWAP_EN, DXN, DXP, and RSVD), the nine (per transceiver) RocketIO MGT pins (TXP, TXN, RXP, RXN, AVCCAUXTX, AVCCAUXRX, VTTX, VTRX, and GNDA), and for Virtex-II Pro X devices only, the two BREFCLKN/ BREFCLKP differential clock input pairs (four pins). The Virtex-II Pro X devices are highlighted in bold type.

1. Unless otherwise noted, "Virtex-II Pro" refers to members of the Virtex-II Pro and/or Virtex-II Pro X families.

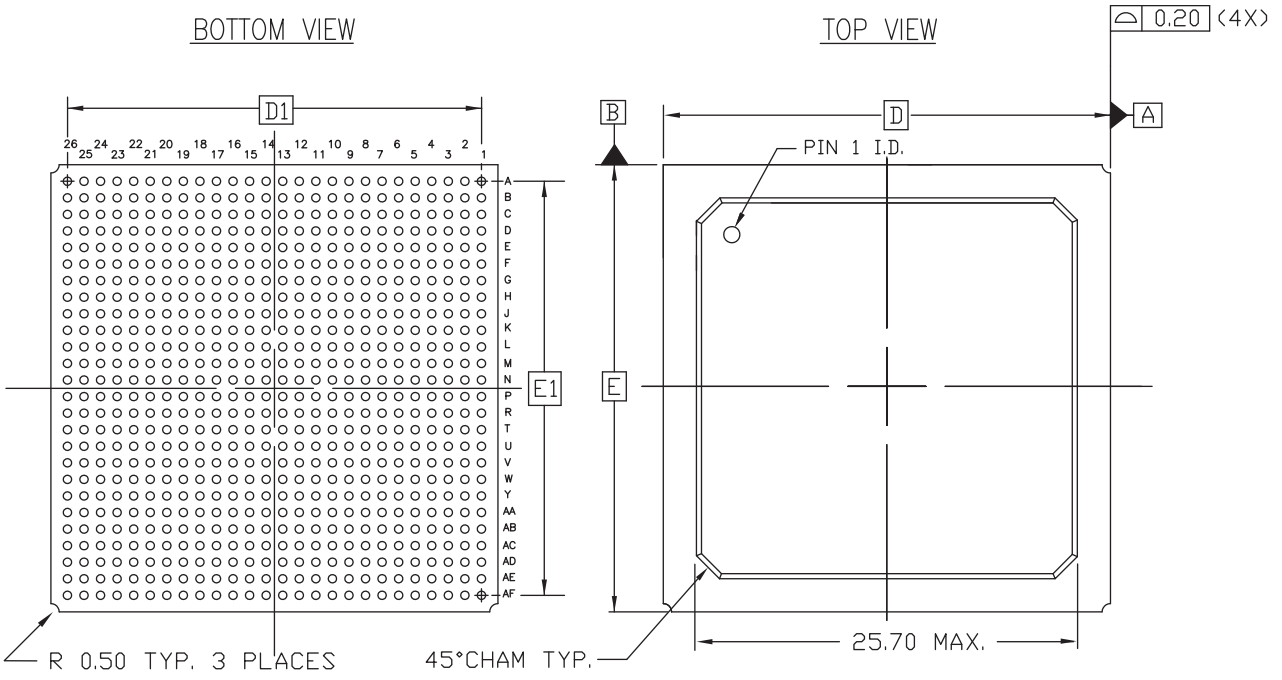
Table 6: **FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7**

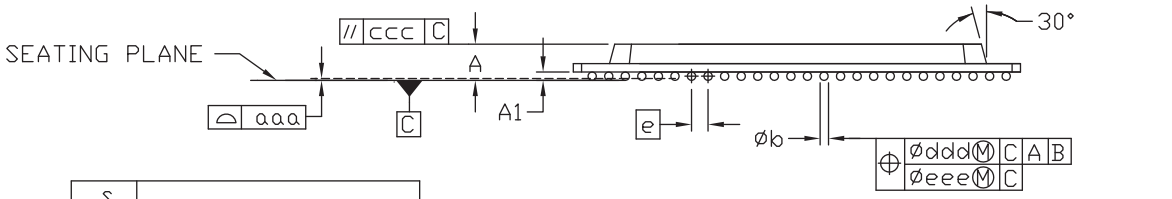
Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
1	IO_L07P_1	F14			
1	IO_L06N_1	C15			
1	IO_L06P_1	D15			
1	IO_L05_1/No_Pair	E15			
1	IO_L03N_1/VREF_1	C16			
1	IO_L03P_1	D16			
1	IO_L02N_1	E16			
1	IO_L02P_1	E17			
1	IO_L01N_1/VRP_1	D17			
1	IO_L01P_1/VRN_1	D18			
2	IO_L01N_2/VRP_2	C21			
2	IO_L01P_2/VRN_2	C22			
2	IO_L02N_2	D21			
2	IO_L02P_2	D22			
2	IO_L03N_2	E19			
2	IO_L03P_2	E20			
2	IO_L04N_2/VREF_2	E21			
2	IO_L04P_2	E22			
2	IO_L06N_2	F19			
2	IO_L06P_2	F20			
2	IO_L43N_2	F21	NC		
2	IO_L43P_2	F22	NC		
2	IO_L46N_2/VREF_2	F18	NC		
2	IO_L46P_2	G18	NC		
2	IO_L48N_2	G19	NC		
2	IO_L48P_2	G20	NC		
2	IO_L49N_2	G21	NC		
2	IO_L49P_2	G22	NC		
2	IO_L50N_2	H19	NC		
2	IO_L50P_2	H20	NC		
2	IO_L52N_2/VREF_2	H21	NC		
2	IO_L52P_2	H22	NC		
2	IO_L54N_2	H18	NC		
2	IO_L54P_2	J17	NC		
2	IO_L55N_2	J19	NC		
2	IO_L55P_2	J20	NC		

Table 7: **FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
N/A	VCCINT	U10			
N/A	VCCINT	U11			
N/A	VCCINT	U16			
N/A	VCCINT	U17			
N/A	VCCINT	U20			
N/A	VCCINT	V9			
N/A	VCCINT	V18			
N/A	VCCINT	Y10			
N/A	VCCINT	Y13			
N/A	VCCINT	Y14			
N/A	VCCINT	Y17			
N/A	VCCAUX	A2			
N/A	VCCAUX	A13			
N/A	VCCAUX	A14			
N/A	VCCAUX	A25			
N/A	VCCAUX	N1			
N/A	VCCAUX	N26			
N/A	VCCAUX	P1			
N/A	VCCAUX	P26			
N/A	VCCAUX	AF2			
N/A	VCCAUX	AF13			
N/A	VCCAUX	AF14			
N/A	VCCAUX	AF25			
N/A	GND	A1			
N/A	GND	A26			
N/A	GND	B2			
N/A	GND	B25			
N/A	GND	C3			
N/A	GND	C24			
N/A	GND	D4			
N/A	GND	D8			
N/A	GND	D19			
N/A	GND	D23			
N/A	GND	F10			
N/A	GND	F17			

FG676/FGG676 Fine-Pitch BGA Package Specifications (1.00mm pitch)





FG676 - 63/37 (Sn/Pb) Solder Balls
FGG676 - Sn/Ag/Cu Solder Balls

SYMBOL	MILLIMETERS		
	MIN.	NOM.	MAX.
A	2.02	2.23	2.44
A_1	0.40	0.50	0.60
D/E	27.00 BSC		
D_1/E_1	25.00 REF		
e	1.00 BSC		
øb	0.50	0.60	0.70
aaa	~	~	0.20
ccc	~	~	0.35
ddd	~	~	0.30
eee	~	~	0.10
M	26		

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-AAL-1

ds083_4_03_053111

Figure 3: **FG676/FGG676 Fine-Pitch BGA Package Specifications**

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
4	VCCO_4		AA11			
4	VCCO_4		AA10			
5	VCCO_5		AB21			
5	VCCO_5		AB20			
5	VCCO_5		AB19			
5	VCCO_5		AB18			
5	VCCO_5		AA21			
5	VCCO_5		AA20			
5	VCCO_5		AA19			
5	VCCO_5		AA18			
5	VCCO_5		AA17			
5	VCCO_5		AA16			
6	VCCO_6		AB22			
6	VCCO_6		AA22			
6	VCCO_6		Y22			
6	VCCO_6		Y21			
6	VCCO_6		W22			
6	VCCO_6		W21			
6	VCCO_6		V22			
6	VCCO_6		V21			
6	VCCO_6		U21			
6	VCCO_6		T21			
7	VCCO_7		R21			
7	VCCO_7		P21			
7	VCCO_7		N22			
7	VCCO_7		N21			
7	VCCO_7		M22			
7	VCCO_7		M21			
7	VCCO_7		L22			
7	VCCO_7		L21			
7	VCCO_7		K22			
7	VCCO_7		J22			
N/A	CCLK		AC7			
N/A	PROG_B		G24			
N/A	DONE		AC8			

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
N/A	TXPPAD19		AK19			
N/A	TXNPAD19		AK20			
N/A	VTTXPAD19		AJ20			
N/A	AVCCAUXTX19		AJ19			
N/A	AVCCAUXRX21		AJ24			
N/A	VTRXPAD21		AJ25			
N/A	RXNPAD21		AK24			
N/A	RXPPAD21		AK25			
N/A	GNDA21		AH25			
N/A	TXPPAD21		AK26			
N/A	TXNPAD21		AK27			
N/A	VTTXPAD21		AJ27			
N/A	AVCCAUXTX21		AJ26			
N/A	VCCAUX		AK29			
N/A	VCCAUX		AK16			
N/A	VCCAUX		AK15			
N/A	VCCAUX		AK2			
N/A	VCCAUX		AJ30			
N/A	VCCAUX		AJ1			
N/A	VCCAUX		T30			
N/A	VCCAUX		T1			
N/A	VCCAUX		R30			
N/A	VCCAUX		R1			
N/A	VCCAUX		B30			
N/A	VCCAUX		B1			
N/A	VCCAUX		A29			
N/A	VCCAUX		A16			
N/A	VCCAUX		A15			
N/A	VCCAUX		A2			
N/A	VCCINT		Y19			
N/A	VCCINT		Y18			
N/A	VCCINT		Y17			
N/A	VCCINT		Y16			
N/A	VCCINT		Y15			
N/A	VCCINT		Y14			

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
4	IO_L27P_4/VREF_4	AL10	NC	NC		
4	IO_L37N_4	AE13				
4	IO_L37P_4	AF13				
4	IO_L38N_4	AG13				
4	IO_L38P_4	AH13				
4	IO_L39N_4	AJ11				
4	IO_L39P_4	AK11				
4	IO_L43N_4	AE14				
4	IO_L43P_4	AF14				
4	IO_L44N_4	AJ13				
4	IO_L44P_4	AK13				
4	IO_L45N_4	AL11				
4	IO_L45P_4/VREF_4	AM11				
4	IO_L46N_4	AE15				
4	IO_L46P_4	AF15				
4	IO_L47N_4	AG14				
4	IO_L47P_4	AH14				
4	IO_L48N_4	AL13				
4	IO_L48P_4	AL12				
4	IO_L49N_4	AD16				
4	IO_L49P_4	AE16				
4	IO_L50_4/No_Pair	AJ14				
4	IO_L53_4/No_Pair	AK14				
4	IO_L54N_4	AM14				
4	IO_L54P_4	AM13				
4	IO_L55N_4	AF16				
4	IO_L55P_4	AG16				
4	IO_L56N_4	AH15				
4	IO_L56P_4	AJ15				
4	IO_L57N_4	AL14				
4	IO_L57P_4/VREF_4	AL15				
4	IO_L67N_4	AD17				
4	IO_L67P_4	AE17				
4	IO_L68N_4	AH16				
4	IO_L68P_4	AJ16				
4	IO_L69N_4	AK16				
4	IO_L69P_4/VREF_4	AL16				
4	IO_L73N_4	AF17				

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
7	IO_L18N_7	L25	NC			
7	IO_L17P_7	F34	NC			
7	IO_L17N_7	F33	NC			
7	IO_L16P_7	G30	NC			
7	IO_L16N_7/VREF_7	G29	NC			
7	IO_L15P_7	G32	NC			
7	IO_L15N_7	G31	NC			
7	IO_L06P_7	F31				
7	IO_L06N_7	F30				
7	IO_L05P_7	J28				
7	IO_L05N_7	J27				
7	IO_L04P_7	E34				
7	IO_L04N_7/VREF_7	E33				
7	IO_L03P_7	E32				
7	IO_L03N_7	E31				
7	IO_L02P_7	F28				
7	IO_L02N_7	F27				
7	IO_L01P_7/VRN_7	D34				
7	IO_L01N_7/VRP_7	D33				
0	VCCO_0	C29				
0	VCCO_0	E20				
0	VCCO_0	F25				
0	VCCO_0	L20				
0	VCCO_0	L21				
0	VCCO_0	L22				
0	VCCO_0	L23				
0	VCCO_0	M18				
0	VCCO_0	M19				
0	VCCO_0	M20				
0	VCCO_0	M21				
0	VCCO_0	M22				
1	VCCO_1	C6				
1	VCCO_1	E15				
1	VCCO_1	F10				
1	VCCO_1	L12				
1	VCCO_1	L13				
1	VCCO_1	L14				

Table 11: **FF1148 — XC2VP40 and XC2VP50**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
7	IO_L13P_7	D28		
7	IO_L13N_7	E28		
7	IO_L12P_7	C33		
7	IO_L12N_7	C34		
7	IO_L11P_7	J27		
7	IO_L11N_7	K27		
7	IO_L10P_7	B30		
7	IO_L10N_7/VREF_7	C30		
7	IO_L09P_7	C28		
7	IO_L09N_7	C29		
7	IO_L08P_7	H27		
7	IO_L08N_7	H28		
7	IO_L07P_7	A32		
7	IO_L07N_7	B32		
7	IO_L06P_7	A31		
7	IO_L06N_7	B31		
7	IO_L05P_7	D27		
7	IO_L05N_7	E27		
7	IO_L04P_7	A29		
7	IO_L04N_7/VREF_7	B29		
7	IO_L03P_7	A28		
7	IO_L03N_7	B28		
7	IO_L02P_7	D26		
7	IO_L02N_7	C26		
7	IO_L01P_7/VRN_7	B26		
7	IO_L01N_7/VRP_7	B27		
7	VCCO_7	E33		
7	VCCO_7	R31		
7	VCCO_7	L31		
7	VCCO_7	G31		
7	VCCO_7	C31		
7	VCCO_7	R27		
7	VCCO_7	L27		
7	VCCO_7	G27		
7	VCCO_7	C27		
7	VCCO_7	J26		
7	VCCO_7	M24		

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
0	IO_L59P_0	N21		
0	IO_L60N_0	E23		
0	IO_L60P_0	F22		
0	IO_L64N_0	D22		
0	IO_L64P_0	E22		
0	IO_L65N_0	H21		
0	IO_L65P_0	H20		
0	IO_L66N_0	G22		
0	IO_L66P_0/VREF_0	G21		
0	IO_L67N_0	D21		
0	IO_L67P_0	E21		
0	IO_L68N_0	J21		
0	IO_L68P_0	K21		
0	IO_L69N_0	C22		
0	IO_L69P_0/VREF_0	C21		
0	IO_L73N_0	F21		
0	IO_L73P_0	F20		
0	IO_L74N_0/GCLK7P	L21		
0	IO_L74P_0/GCLK6S	M21		
0	IO_L75N_0/GCLK5P	D20		
0	IO_L75P_0/GCLK4S	E20		
1	IO_L75N_1/GCLK3P	K20		
1	IO_L75P_1/GCLK2S	J20		
1	IO_L74N_1/GCLK1P	N20		
1	IO_L74P_1/GCLK0S	M20		
1	IO_L73N_1	E19		
1	IO_L73P_1	D19		
1	IO_L69N_1/VREF_1	G19		
1	IO_L69P_1	F19		
1	IO_L68N_1	L19		
1	IO_L68P_1	K19		
1	IO_L67N_1	J19		
1	IO_L67P_1	H19		
1	IO_L66N_1/VREF_1	C19		
1	IO_L66P_1	C18		
1	IO_L65N_1	N19		
1	IO_L65P_1	M19		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
7	IO_L87P_7		AA33		
7	IO_L87N_7		AA34		
7	IO_L86P_7		Y31		
7	IO_L86N_7		Y32		
7	IO_L85P_7		Y39		
7	IO_L85N_7		Y40		
7	IO_L60P_7		Y36		
7	IO_L60N_7		Y37		
7	IO_L59P_7		Y33		
7	IO_L59N_7		Y34		
7	IO_L58P_7		W41		
7	IO_L58N_7/VREF_7		W42		
7	IO_L57P_7		W39		
7	IO_L57N_7		W40		
7	IO_L56P_7		W31		
7	IO_L56N_7		W32		
7	IO_L55P_7		W37		
7	IO_L55N_7		W38		
7	IO_L54P_7		W35		
7	IO_L54N_7		W36		
7	IO_L53P_7		W33		
7	IO_L53N_7		W34		
7	IO_L52P_7		V41		
7	IO_L52N_7/VREF_7		V42		
7	IO_L51P_7		V38		
7	IO_L51N_7		V39		
7	IO_L50P_7		V31		
7	IO_L50N_7		U32		
7	IO_L49P_7		V35		
7	IO_L49N_7		V36		
7	IO_L48P_7		V32		
7	IO_L48N_7		V33		
7	IO_L47P_7		U31		
7	IO_L47N_7		T31		
7	IO_L46P_7		U41		
7	IO_L46N_7/VREF_7		U42		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
N/A	GND		E22		
N/A	GND		E21		
N/A	GND		E5		
N/A	GND		D39		
N/A	GND		D32		
N/A	GND		D28		
N/A	GND		D15		
N/A	GND		D11		
N/A	GND		D4		
N/A	GND		C42		
N/A	GND		C41		
N/A	GND		C40		
N/A	GND		C3		
N/A	GND		C2		
N/A	GND		C1		
N/A	GND		B42		
N/A	GND		B1		
N/A	GND		N14		
N/A	GND		N29		
N/A	GND		AK14		
N/A	GND		AK29		
N/A	GND		P13		
N/A	GND		P30		
N/A	GND		AJ13		
N/A	GND		AJ30		

Notes:
1. See Table 4 for an explanation of the signals available on this pin.

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
7	IO_L45N_7	T36	
7	IO_L44P_7	W32	
7	IO_L44N_7	W33	
7	IO_L43P_7	R41	
7	IO_L43N_7	R42	
7	IO_L42P_7	P40	
7	IO_L42N_7	R40	
7	IO_L41P_7	V36	
7	IO_L41N_7	V37	
7	IO_L40P_7	R38	
7	IO_L40N_7/VREF_7	R39	
7	IO_L39P_7	P38	
7	IO_L39N_7	R37	
7	IO_L38P_7	V34	
7	IO_L38N_7	V35	
7	IO_L37P_7	P41	
7	IO_L37N_7	P42	
7	IO_L36P_7	P36	
7	IO_L36N_7	P37	
7	IO_L35P_7	V32	
7	IO_L35N_7	V33	
7	IO_L34P_7	M41	
7	IO_L34N_7/VREF_7	N41	
7	IO_L33P_7	N39	
7	IO_L33N_7	N40	
7	IO_L32P_7	U35	
7	IO_L32N_7	U36	
7	IO_L31P_7	N36	
7	IO_L31N_7	N37	
7	IO_L30P_7	M39	
7	IO_L30N_7	M40	
7	IO_L29P_7	U32	
7	IO_L29N_7	U33	
7	IO_L28P_7	M37	
7	IO_L28N_7/VREF_7	M38	
7	IO_L27P_7	L37	
7	IO_L27N_7	M36	